



MMBD4448DW

## SURFACE MOUNT SWITCHING DIODE

### **Features**

- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automated Insertion
- For General Purpose Switching Applications
- **High Conductance**
- Miniature Package
- Lead Free/RoHS Compliant (Note 1)
- Qualified to AEC-Q101 Standards for High Reliability
- "Green" Device (Notes 2 and 3)

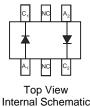
### **Mechanical Data**

- Case: SOT-363
- Case Material: Molded Plastic, "Green" Molding Compound. UL • Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Polarity: See Diagram
- Weight: 0.006 grams (approximate)

SOT-363



Top View



#### Ordering Information (Note 4)

| Part Number    | Case    | Packaging        |
|----------------|---------|------------------|
| MMBD4448DW-7-F | SOT-363 | 3000/Tape & Reel |

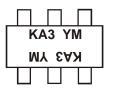
Notes:

1. No purposefully added lead.

 No purpose duty added read.
Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com.
Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

4. For packaging details, go to our website at http://www.diodes.com.

# **Marking Information**



KA3 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: N = 2002)M = Month (ex: 9 = September)

#### Date Code Key

| 2410 0040 |      |      |      |      |      |      |      |      |      |      |      |      |      |      |      |      |
|-----------|------|------|------|------|------|------|------|------|------|------|------|------|------|------|------|------|
| Year      | 2000 | 2001 | 2002 | 2003 | 2004 | 2005 | 2006 | 2007 | 2008 | 2009 | 2010 | 2011 | 2012 | 2013 | 2014 | 2015 |
| Code      | L    | Μ    | N    | Р    | R    | S    | Т    | U    | V    | W    | Х    | Y    | Z    | А    | В    | С    |
| Month     | Jan  | F    | eb   | Mar  | Apr  | M    | ay   | Jun  | Jul  | A    | ug   | Sep  | Oct  | N    | ov   | Dec  |
| Code      | 1    |      | 2    | 3    | 4    |      | 5    | 6    | 7    | 8    | 3    | 9    | 0    | 1    | N    | D    |



# Maximum Ratings @T<sub>A</sub> = 25°C unless otherwise specified

| Characteristic   |                       | Symbol   | Value  | Unit |  |
|--|-----------------------|--|--------|------|--|
| Non-Repetitive Peak Reverse Voltage  |                       | V <sub>RM</sub>  | 100    | V    |  |
| Peak Repetitive Reverse Voltage<br>Working Peak Reverse Voltage<br>DC Blocking Voltage |                       | V <sub>RRM</sub><br>V <sub>RWM</sub><br>V <sub>R</sub> | 75     | V    |  |
| RMS Reverse Voltage  |                       | V <sub>R(RMS)</sub>                                    | 53     | V    |  |
| Forward Continuous Current (Note 5)  |                       | I <sub>FM</sub>  | 500    | mA   |  |
| Average Rectified Output Current (Note 5)  |                       | lo   | 250    | mA   |  |
| Non-Repetitive Peak Forward Surge Current  | @ t < 1μs<br>@ t < 1s | IFSM   | 4<br>1 | А    |  |

# **Thermal Characteristics**

| Characteristic                                      | Symbol                            | Value       | Unit |
|---|-----------------------------------|-------------|------|
| Characteristic                                      | Symbol                            | Value       | Onit |
| Power Dissipation (Note 5)                          | PD                                | 200         | mW   |
| Thermal Resistance Junction to Ambient Air (Note 5) | $R_{	ext{	heta}JA}$               | 625         | °C/W |
| Operating and Storage Temperature Range             | T <sub>J</sub> , T <sub>STG</sub> | -65 to +150 | °C   |

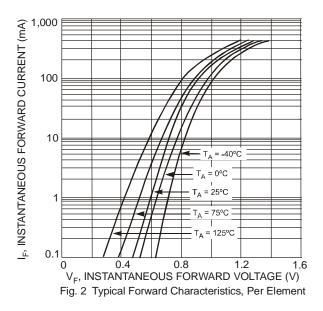
## Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

| Characteristic                     | Symbol             | Min            | Max            | Unit | Test Condition                                 |    |  |
|------------------------------------|--------------------|----------------|----------------|------|--|----|--|
| Reverse Breakdown Voltage (Note 6) | V <sub>(BR)R</sub> | 75             |                | V    | $I_R = 10 \mu A$                               |    |  |
|                                    |                    | 0.62           | 0.720          |      | $I_F = 5.0 \text{mA}$                          |    |  |
| Forward Voltage                    | V <sub>F</sub>     |                | 0.855          | V    | I <sub>F</sub> = 10mA                          |    |  |
| Torward Voltage                    |                    |                | 1.0            |      | I <sub>F</sub> = 50mA                          |    |  |
|                                    |                    | —              | 1.25           |      | I <sub>F</sub> = 150mA                         |    |  |
|                                    |                    |                | 2.5            | μA   | V <sub>R</sub> = 75V                           |    |  |
| Deverse Current (Note 6)           | I <sub>R</sub>     | I <sub>R</sub> | I <sub>R</sub> |      | 50   | μΑ | V <sub>R</sub> = 75V, T <sub>J</sub> = 150°C |
| Reverse Current (Note 6)           |                    |                |                | IR   | ١R   |    | 30   |
|                                    |                    |                | 25             | nA   | V <sub>R</sub> = 20V                           |    |  |
| Total Capacitance                  | CT                 |                | 4.0            | pF   | V <sub>R</sub> = 0, f = 1.0MHz                 |    |  |
| Reverse Recovery Time              | +                  |                | 4.0            | ns   | $I_F = I_R = 10 \text{mA},$                    |    |  |
|                                    | t <sub>rr</sub>    |                | ٠.٠            | 115  | $I_{rr} = 0.1 \text{ x } I_R, R_L = 100\Omega$ |    |  |

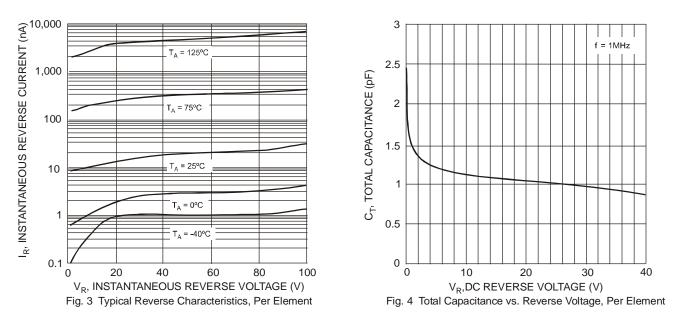
Notes:

Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com.
Short duration pulse test used to minimize self-heating.

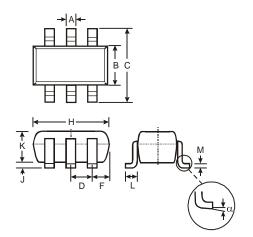
250 200 150 150 100 0 40 80 120 160 200 T<sub>A</sub>, AMBIENT TEMPERATURE (°C) Fig. 1 Power Derating Curve, Total Package (Note 5)





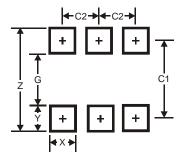


# Package Outline Dimensions



|        | SOT-363              |      |  |  |  |  |  |  |
|--------|----------------------|------|--|--|--|--|--|--|
| Dim    | Dim Min Max          |      |  |  |  |  |  |  |
| Α      | 0.10                 | 0.30 |  |  |  |  |  |  |
| В      | 1.15                 | 1.35 |  |  |  |  |  |  |
| С      | 2.00                 | 2.20 |  |  |  |  |  |  |
| D      | 0.65                 | Тур  |  |  |  |  |  |  |
| F      | 0.40                 | 0.45 |  |  |  |  |  |  |
| Н      | 1.80                 | 2.20 |  |  |  |  |  |  |
| J      | 0 0.10               |      |  |  |  |  |  |  |
| Κ      | 0.90 1.00            |      |  |  |  |  |  |  |
| L      | 0.25 0.40            |      |  |  |  |  |  |  |
| М      | 0.10                 | 0.22 |  |  |  |  |  |  |
| α      | 0°                   | 8°   |  |  |  |  |  |  |
| All Di | All Dimensions in mm |      |  |  |  |  |  |  |

# **Suggested Pad Layout**



| Dimensions | Value (in mm) |
|------------|---------------|
| Z          | 2.5           |
| G          | 1.3           |
| Х          | 0.42          |
| Y          | 0.6           |
| C1         | 1.9           |
| C2         | 0.65          |



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